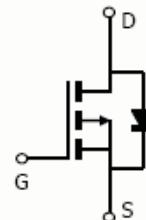


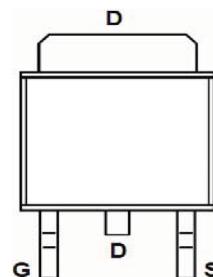
P-Channel Enhancement Mode Power MOSFET

Description

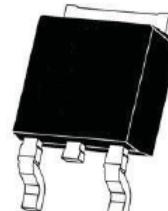
The RM40P40LD uses advanced trench technology and design to provide excellent RDS(ON) with low gate charge .This device is well suited for high current load applications.



Schematic diagram



Marking and pin assignment



TO-252-2L top view

100% UIS TESTED!

100% ΔV_{ds} TESTED!

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
40P40	RM40P40LD	TO-252-2L	-	-	-

Absolute Maximum Ratings ($T_c=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	-40	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	-40	A
Drain Current-Continuous($T_c=100^\circ\text{C}$)	I_D (100°C)	-25	A
Pulsed Drain Current	I_{DM}	-50	A
Maximum Power Dissipation	P_D	80	W
Derating factor		0.53	W/°C
Single pulse avalanche energy (Note 5)	E_{AS}	544	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 175	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Case ^(Note 2)	R _{θJC}	1.88	°C/W
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Electrical Characteristics ($T_c=25^\circ\text{C}$ unless otherwise noted)

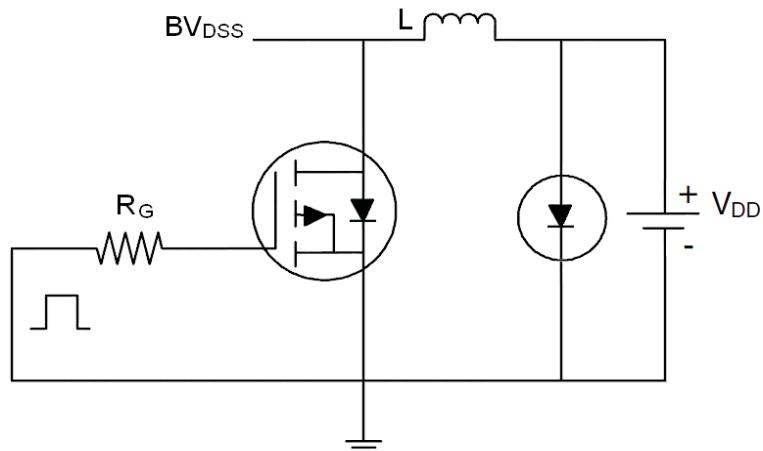
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-40	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=-40\text{V}, V_{\text{GS}}=0\text{V}$	-	-	-1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	±100	nA
On Characteristics ^(Note 3)						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-1.5	-1.9	-3.0	V
Drain-Source On-State Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-12\text{A}$	-	12	14	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$V_{\text{DS}}=-5\text{V}, I_{\text{D}}=-12\text{A}$	34	-	-	S
Dynamic Characteristics ^(Note 4)						
Input Capacitance	C_{iss}	$V_{\text{DS}}=-20\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	2960	-	PF
Output Capacitance	C_{oss}		-	370	-	PF
Reverse Transfer Capacitance	C_{rss}		-	310	-	PF
Switching Characteristics ^(Note 4)						
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=-20\text{V}, I_{\text{D}}=-20\text{A}$ $V_{\text{GS}}=-10\text{V}, R_{\text{G}}=3\Omega$	-	10	-	nS
Turn-on Rise Time	t_{r}		-	18	-	nS
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	38	-	nS
Turn-Off Fall Time	t_{f}		-	24	-	nS
Total Gate Charge	Q_{g}	$V_{\text{DS}}=-20, I_{\text{D}}=-12\text{A}, V_{\text{GS}}=-10\text{V}$	-	72	-	nC
Gate-Source Charge	Q_{gs}		-	14	-	nC
Gate-Drain Charge	Q_{gd}		-	15	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage ^(Note 3)	V_{SD}	$V_{\text{GS}}=0\text{V}, I_{\text{s}}=-20\text{A}$	-		-1.2	V
Diode Forward Current ^(Note 2)	I_{s}		-	-	-40	A
Reverse Recovery Time	t_{rr}	$T_J = 25^\circ\text{C}, IF = -20\text{A}$ $di/dt = -100\text{A}/\mu\text{s}$ ^(Note 3)	-	40	-	nS
Reverse Recovery Charge	Q_{rr}		-	42	-	nC
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Notes:

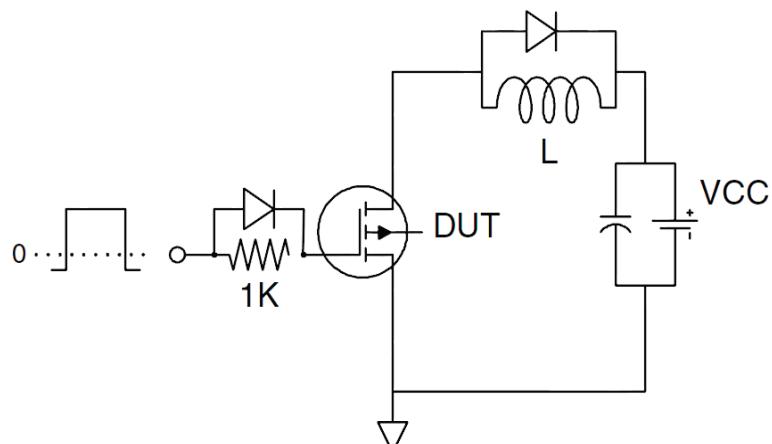
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production
5. E_{AS} condition: $T_J=25^\circ\text{C}, V_{\text{DD}}=-20\text{V}, V_{\text{G}}=-10\text{V}, L=1\text{mH}, R_g=25\Omega, I_{\text{AS}}=33\text{A}$

Test Circuit

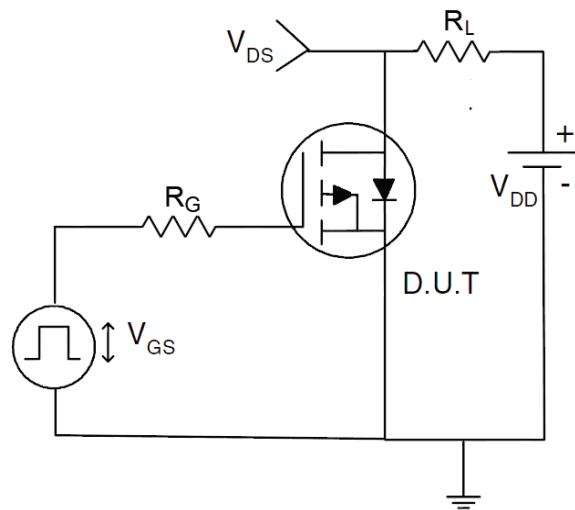
1) E_{AS} Test Circuit



2) Gate Charge Test Circuit



3) Switch Time Test Circuit



RATING AND CHARACTERISTICS CURVES (RM40P40LD)

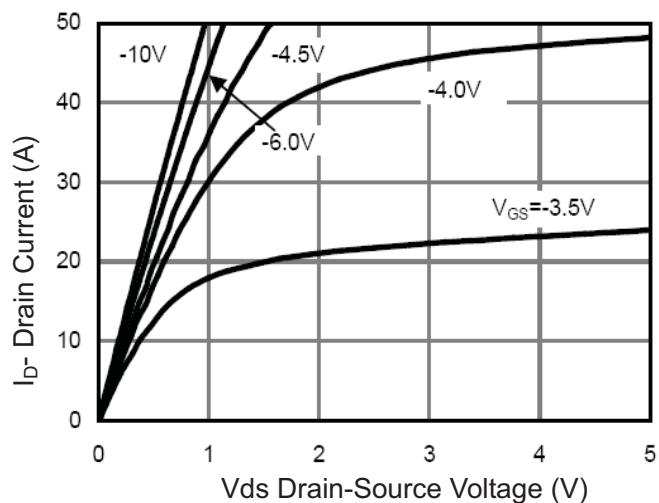


Figure 1 Output Characteristics

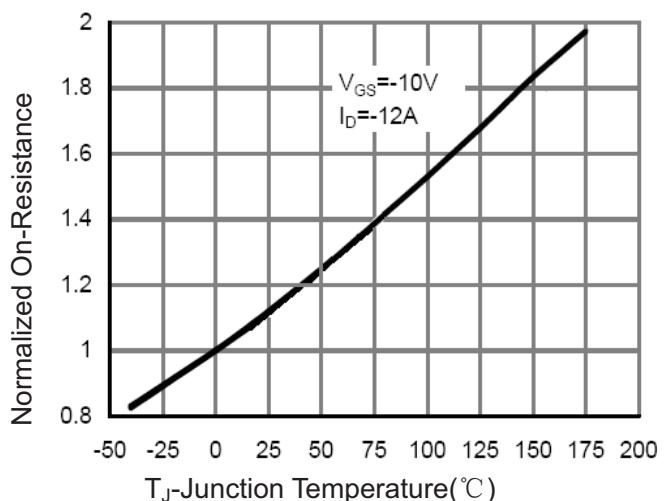


Figure 4 Rdson-Junction Temperature

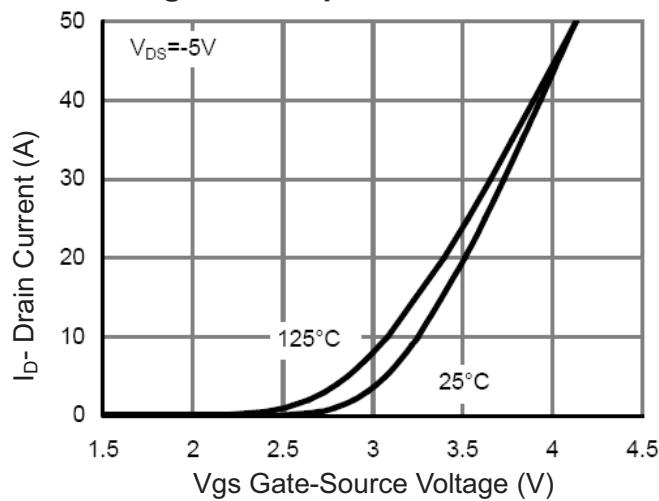


Figure 2 Transfer Characteristics

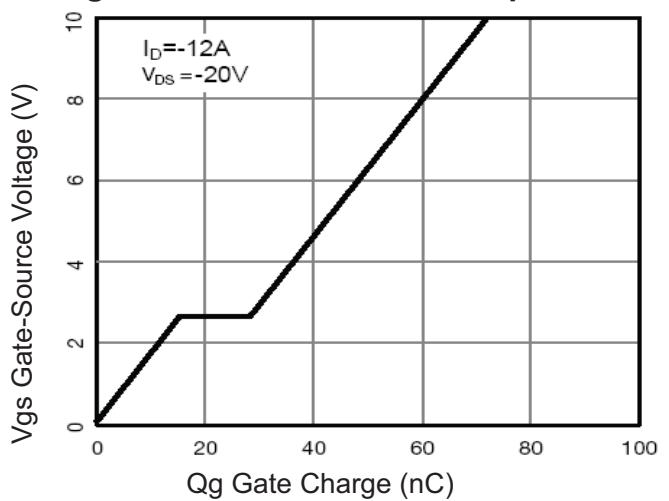


Figure 5 Gate Charge

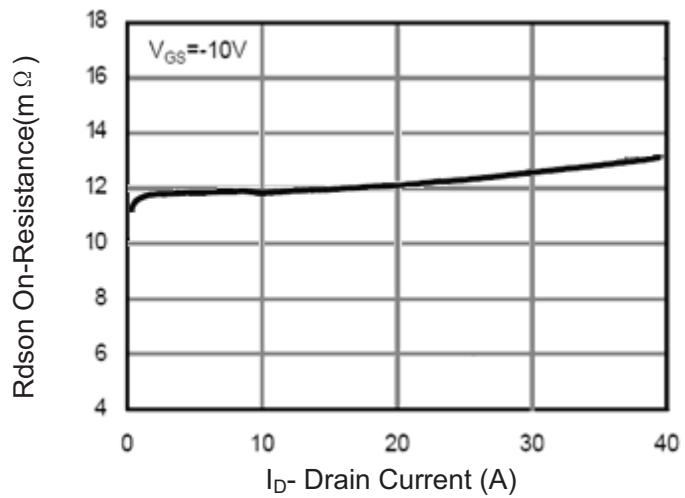


Figure 3 Rdson- Drain Current

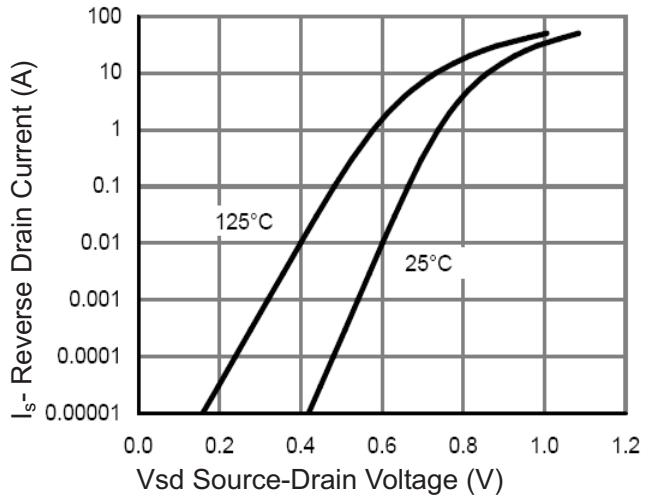


Figure 6 Source- Drain Diode Forward

RATING AND CHARACTERISTICS CURVES (RM40P40LD)

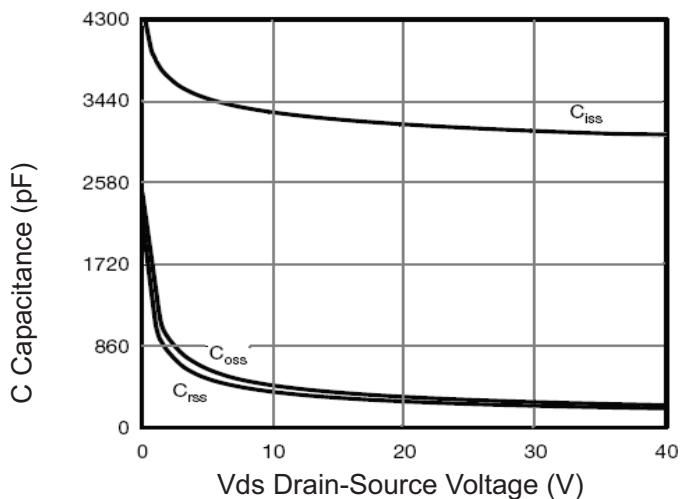


Figure 7 Capacitance vs Vds

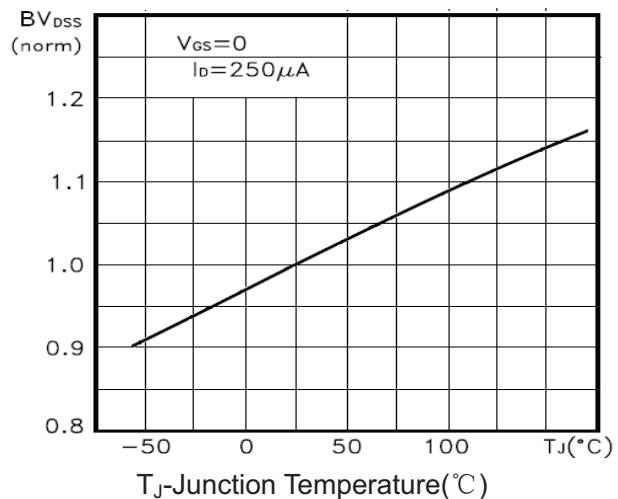


Figure 9 BV_{DSS} vs Junction Temperature

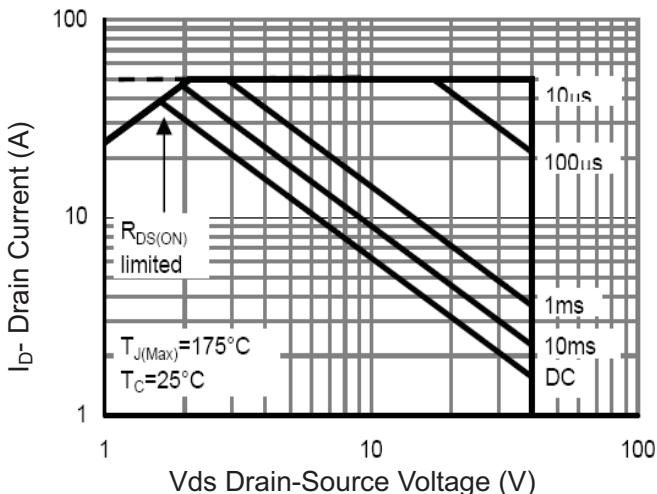


Figure 8 Safe Operation Area

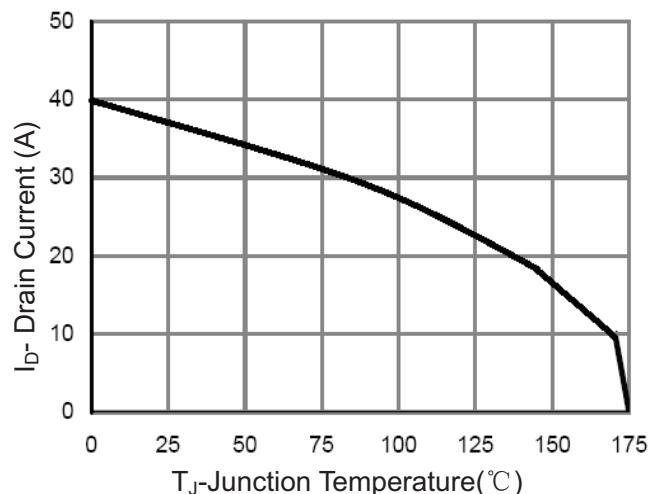


Figure 10 I_D Current Derating vs Junction Temperature

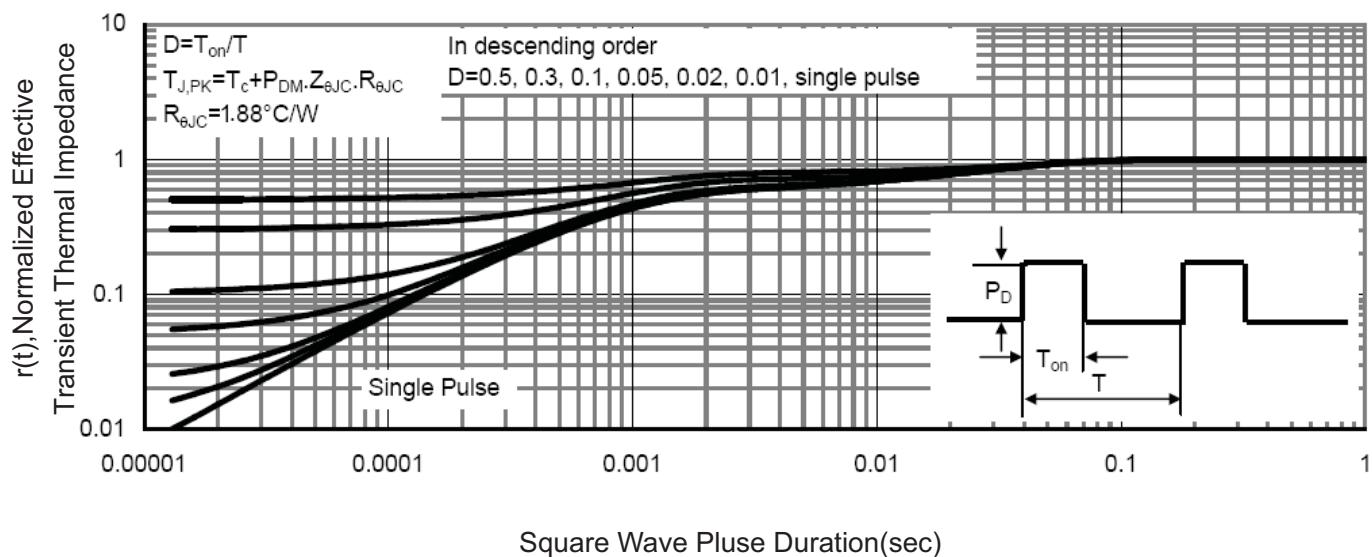
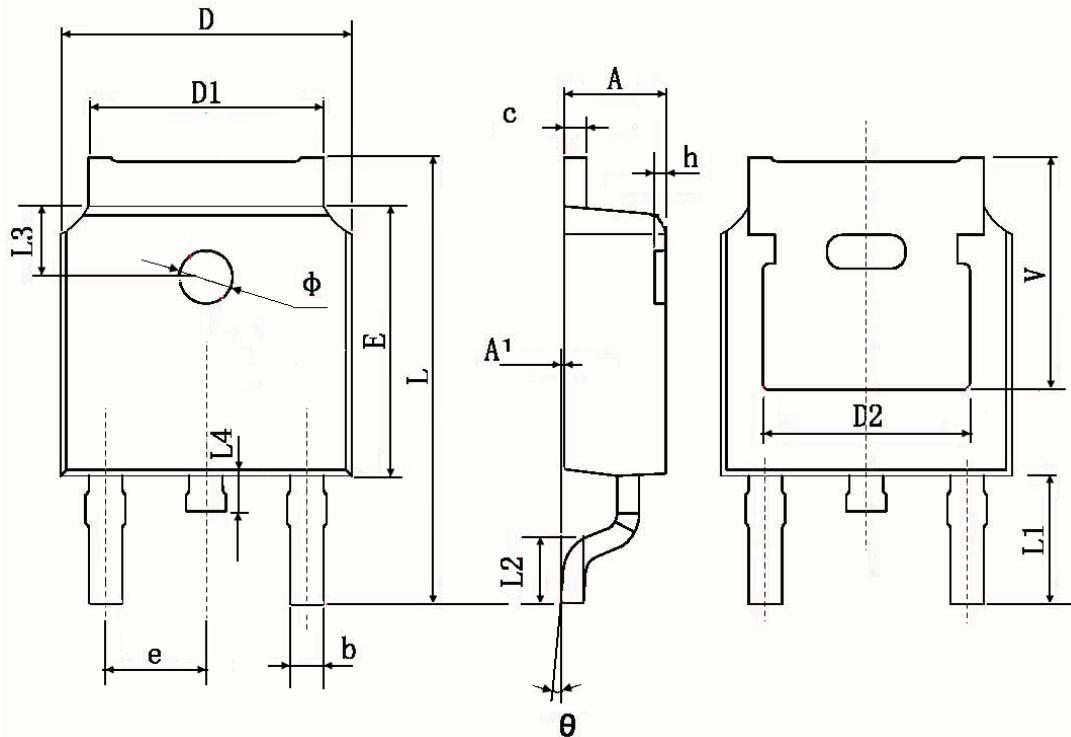


Figure 11 Normalized Maximum Transient Thermal Impedance

TO-252 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	

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